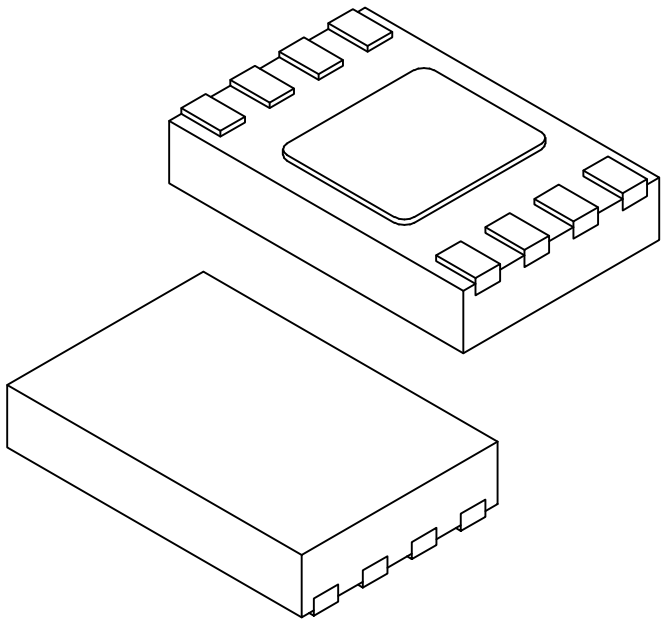


8-Lead Ultra Thin Plastic Dual Flat, No Lead Package (Q4B) - 2x3 mm Body [UDFN]  
Atmel Legacy Global Package Code YNZ

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



| Units                   |    | MILLIMETERS |      |      |
|-------------------------|----|-------------|------|------|
| Dimension Limits        |    | MIN         | NOM  | MAX  |
| Number of Terminals     | N  | 8           |      |      |
| Pitch                   | e  | 0.50 BSC    |      |      |
| Overall Height          | A  | 0.50        | 0.55 | 0.60 |
| Standoff                | A1 | 0.00        | 0.02 | 0.05 |
| Terminal Thickness      | A3 | 0.152 REF   |      |      |
| Overall Length          | D  | 2.00 BSC    |      |      |
| Exposed Pad Length      | D2 | 1.40        | 1.50 | 1.60 |
| Overall Width           | E  | 3.00 BSC    |      |      |
| Exposed Pad Width       | E2 | 1.20        | 1.30 | 1.40 |
| Terminal Width          | b  | 0.18        | 0.25 | 0.30 |
| Terminal Length         | L  | 0.25        | 0.35 | 0.45 |
| Terminal-to-Exposed-Pad | K  | 0.20        | -    | -    |

Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. Package is saw singulated
- 3. Dimensioning and tolerancing per ASME Y14.5M
  - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
  - REF: Reference Dimension, usually without tolerance, for information purposes only.